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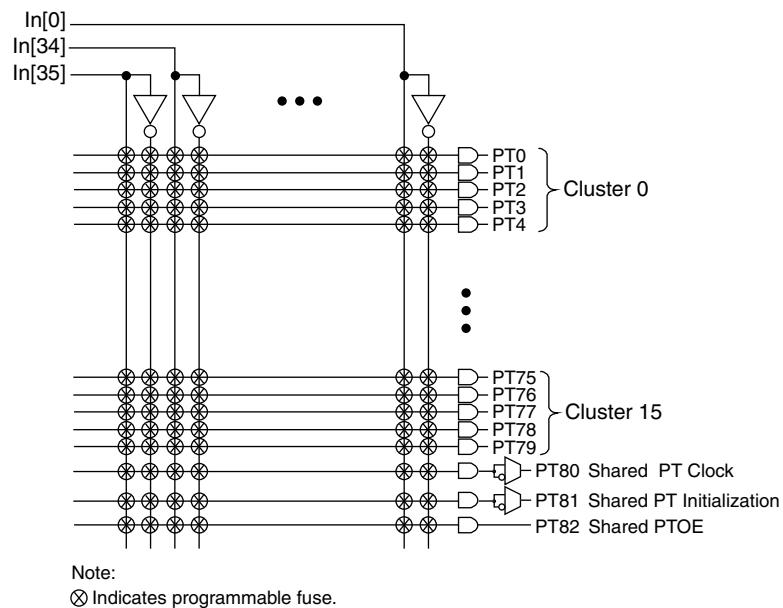
## Understanding [Embedded - CPLDs \(Complex Programmable Logic Devices\)](#)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

## Applications of Embedded - CPLDs

### Details

Product Status	Active
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	1.7V ~ 1.9V
Number of Logic Elements/Blocks	16
Number of Macrocells	256
Number of Gates	-
Number of I/O	128
Operating Temperature	-40°C ~ 130°C (TJ)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-TQFP (24x24)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4256zc-75tn176e">https://www.e-xfl.com/product-detail/lattice-semiconductor/lc4256zc-75tn176e</a>

**Figure 3. AND Array**

## Enhanced Logic Allocator

Within the logic allocator, product terms are allocated to macrocells in product term clusters. Each product term cluster is associated with a macrocell. The cluster size for the ispMACH 4000 family is 4+1 (total 5) product terms. The software automatically considers the availability and distribution of product term clusters as it fits the functions within a GLB. The logic allocator is designed to provide three speed paths: 5-PT fast bypass path, 20-PT Speed Locking path and an up to 80-PT path. The availability of these three paths lets designers trade timing variability for increased performance.

The enhanced Logic Allocator of the ispMACH 4000 family consists of the following blocks:

- Product Term Allocator
- Cluster Allocator
- Wide Steering Logic

Figure 4 shows a macrocell slice of the Logic Allocator. There are 16 such slices in the GLB.

**Figure 4. Macrocell Slice**

## Product Term Allocator

The product term allocator assigns product terms from a cluster to either logic or control applications as required by the design being implemented. Product terms that are used as logic are steered into a 5-input OR gate associated with the cluster. Product terms that are used for control are steered either to the macrocell or I/O cell associated with the cluster. Table 3 shows the available functions for each of the five product terms in the cluster. The OR gate output connects to the associated I/O cell, providing a fast path for narrow combinatorial functions, and to the logic allocator.

**Table 3. Individual PT Steering**

Product Term	Logic	Control
PT <sub>n</sub>	Logic PT	Single PT for XOR/OR
PT <sub>n+1</sub>	Logic PT	Individual Clock (PT Clock)
PT <sub>n+2</sub>	Logic PT	Individual Initialization or Individual Clock Enable (PT Initialization/CE)
PT <sub>n+3</sub>	Logic PT	Individual Initialization (PT Initialization)
PT <sub>n+4</sub>	Logic PT	Individual OE (PTOE)

## Cluster Allocator

The cluster allocator allows clusters to be steered to neighboring macrocells, thus allowing the creation of functions with more product terms. Table 4 shows which clusters can be steered to which macrocells. Used in this manner, the cluster allocator can be used to form functions of up to 20 product terms. Additionally, the cluster allocator accepts inputs from the wide steering logic. Using these inputs, functions up to 80 product terms can be created.

**Table 4. Available Clusters for Each Macrocell**

Macrocell	Available Clusters			
M0	—	C0	C1	C2
M1	C0	C1	C2	C3
M2	C1	C2	C3	C4
M3	C2	C3	C4	C5
M4	C3	C4	C5	C6
M5	C4	C5	C6	C7
M6	C5	C6	C7	C8
M7	C6	C7	C8	C9
M8	C7	C8	C9	C10
M9	C8	C9	C10	C11
M10	C9	C10	C11	C12
M11	C10	C11	C12	C13
M12	C11	C12	C13	C14
M13	C12	C13	C14	C15
M14	C13	C14	C15	—
M15	C14	C15	—	—

## Wide Steering Logic

The wide steering logic allows the output of the cluster allocator  $n$  to be connected to the input of the cluster allocator  $n+4$ . Thus, cluster chains can be formed with up to 80 product terms, supporting wide product term functions and allowing performance to be increased through a single GLB implementation. Table 5 shows the product term chains.

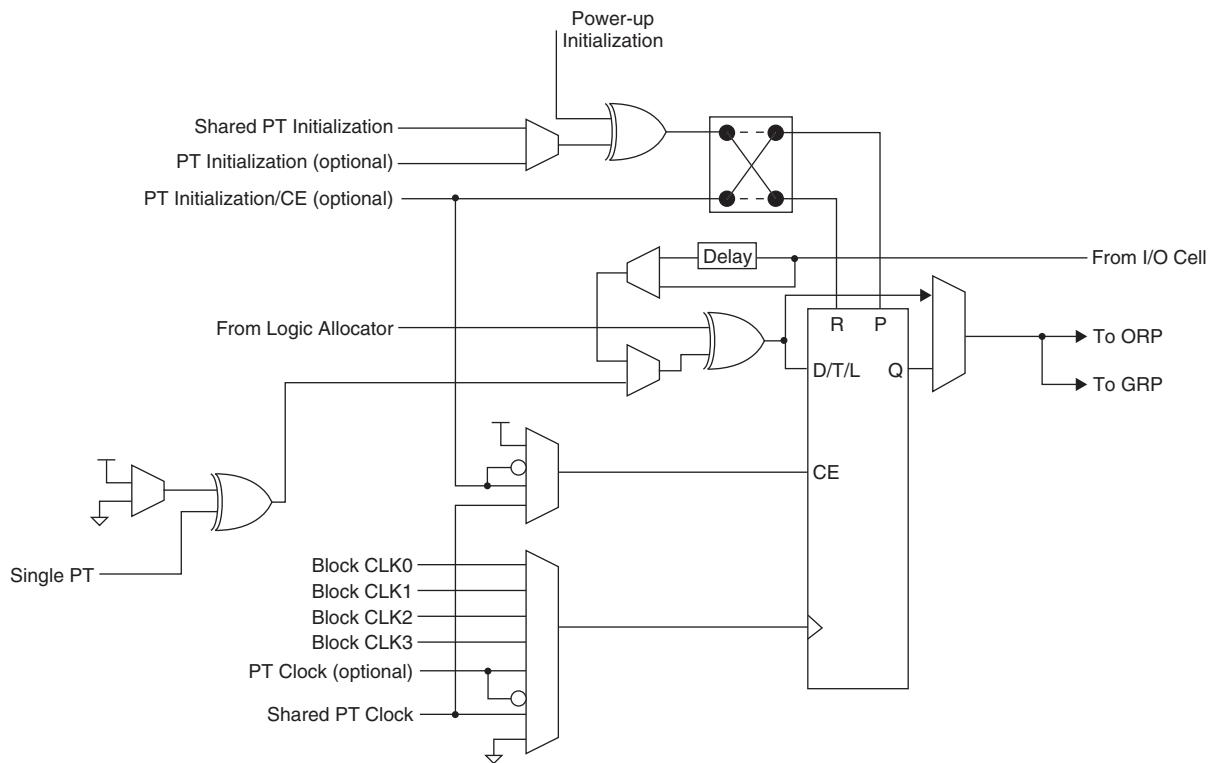
**Table 5. Product Term Expansion Capability**

Expansion Chains	Macrocells Associated with Expansion Chain (with Wrap Around)	Max PT/Macrocell
Chain-0	M0 M4 M8 M12 M0	75
Chain-1	M1 M5 M9 M13 M1	80
Chain-2	M2 M6 M10 M14 M2	75
Chain-3	M3 M7 M11 M15 M3	70

Every time the super cluster allocator is used, there is an incremental delay of  $t_{EXP}$ . When the super cluster allocator is used, all destinations other than the one being steered to, are given the value of ground (i.e., if the super cluster is steered to M (n+4), then M (n) is ground).

## Macrocell

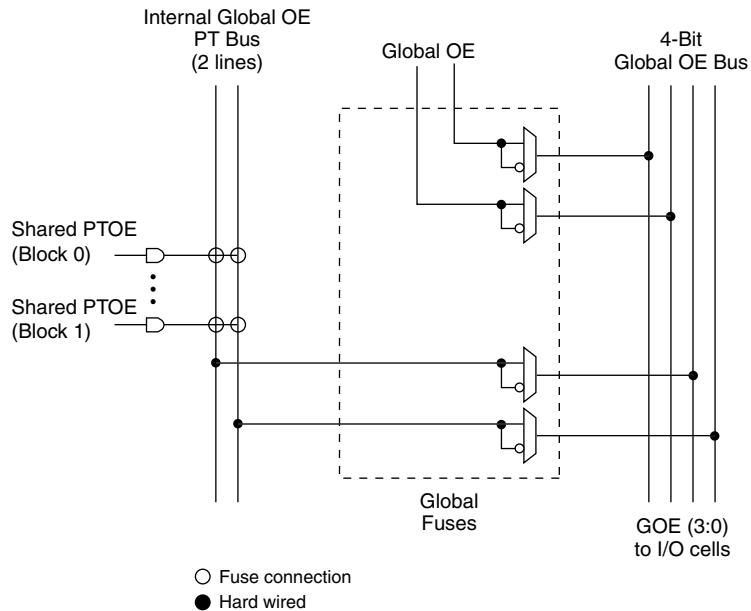
The 16 macrocells in the GLB are driven by the 16 outputs from the logic allocator. Each macrocell contains a programmable XOR gate, a programmable register/latch, along with routing for the logic and control functions. Figure 5 shows a graphical representation of the macrocell. The macrocells feed the ORP and GRP. A direct input from the I/O cell allows designers to use the macrocell to construct high-speed input registers. A programmable delay in this path allows designers to choose between the fastest possible set-up time and zero hold time.

**Figure 5. Macrocell**

## Enhanced Clock Multiplexer

The clock input to the flip-flop can select any of the four block clocks along with the shared PT clock, and true and complement forms of the optional individual term clock. An 8:1 multiplexer structure is used to select the clock. The eight sources for the clock multiplexer are as follows:

- Block CLK0
- Block CLK1

**Figure 10. Global OE Generation for ispMACH 4032**

## Zero Power/Low Power and Power Management

The ispMACH 4000 family is designed with high speed low power design techniques to offer both high speed and low power. With an advanced E<sup>2</sup> low power cell and non sense-amplifier design approach (full CMOS logic approach), the ispMACH 4000 family offers SuperFAST pin-to-pin speeds, while simultaneously delivering low standby power without needing any “turbo bits” or other power management schemes associated with a traditional sense-amplifier approach.

The zero power ispMACH 4000Z is based on the 1.8V ispMACH 4000C family. With innovative circuit design changes, the ispMACH 4000Z family is able to achieve the industry’s “lowest static power”.

## IEEE 1149.1-Compliant Boundary Scan Testability

All ispMACH 4000 devices have boundary scan cells and are compliant to the IEEE 1149.1 standard. This allows functional testing of the circuit board on which the device is mounted through a serial scan path that can access all critical logic nodes. Internal registers are linked internally, allowing test data to be shifted in and loaded directly onto test nodes, or test node data to be captured and shifted out for verification. In addition, these devices can be linked into a board-level serial scan path for more board-level testing. The test access port operates with an LVCMOS interface that corresponds to the power supply voltage.

## I/O Quick Configuration

To facilitate the most efficient board test, the physical nature of the I/O cells must be set before running any continuity tests. As these tests are fast, by nature, the overhead and time that is required for configuration of the I/Os’ physical nature should be minimal so that board test time is minimized. The ispMACH 4000 family of devices allows this by offering the user the ability to quickly configure the physical nature of the I/O cells. This quick configuration takes milliseconds to complete, whereas it takes seconds for the entire device to be programmed. Lattice's ispVM® System programming software can either perform the quick configuration through the PC parallel port, or can generate the ATE or test vectors necessary for a third-party test system.

## Supply Current, ispMACH 4000Z (Cont.)

Over Recommended Operating Conditions

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>ispMACH 4256ZC</b>						
ICC <sup>1, 2, 3, 5</sup>	Operating Power Supply Current	Vcc = 1.8V, TA = 25°C	—	341	—	µA
		Vcc = 1.9V, TA = 70°C	—	361	—	µA
		Vcc = 1.9V, TA = 85°C	—	372	—	µA
		Vcc = 1.9V, TA = 125°C	—	468	—	µA
ICC <sup>4, 5</sup>	Standby Power Supply Current	Vcc = 1.8V, TA = 25°C	—	13	—	µA
		Vcc = 1.9V, TA = 70°C	—	32	55	µA
		Vcc = 1.9V, TA = 85°C	—	43	90	µA
		Vcc = 1.9V, TA = 125°C	—	135	—	µA

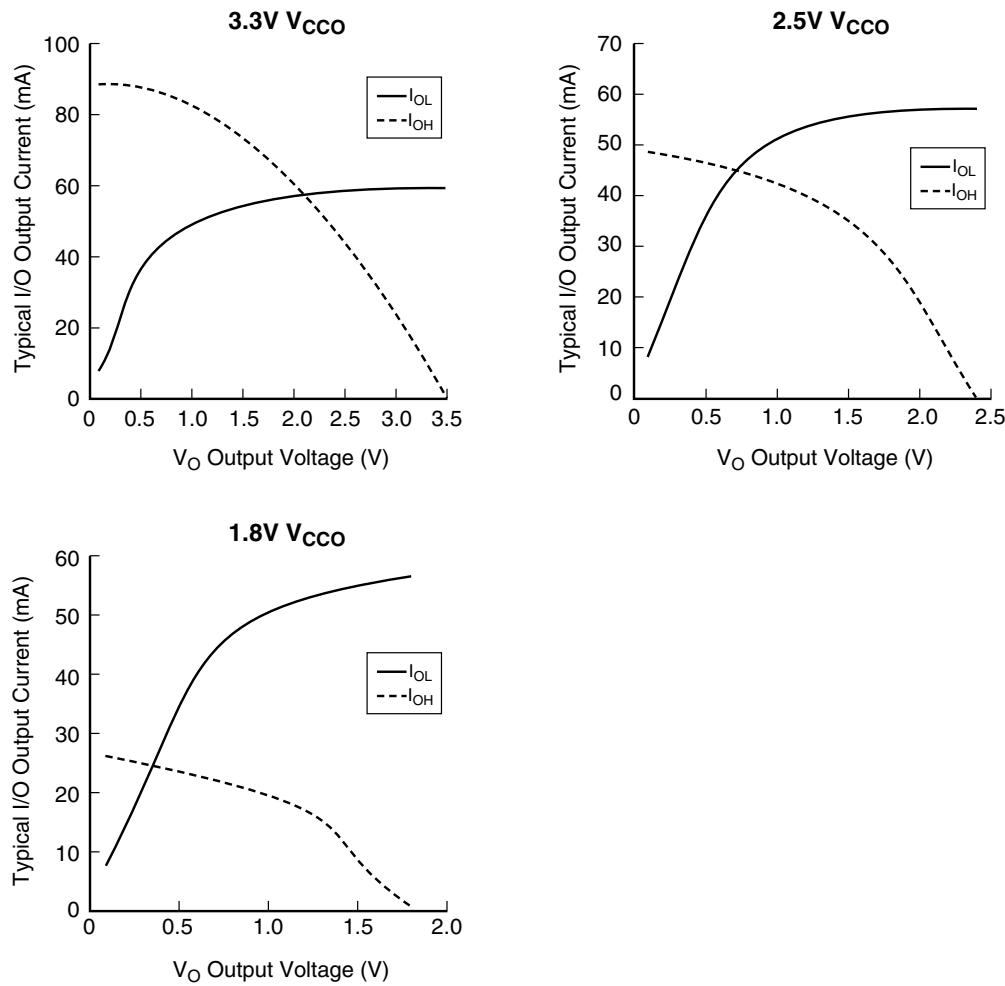
1. TA = 25°C, frequency = 1.0 MHz.

2. Device configured with 16-bit counters.

3. ICC varies with specific device configuration and operating frequency.

4. VCCO = 3.6V, VIN = 0V or VCCO, bus maintenance turned off. VIN above VCCO will add transient current above the specified standby ICC.

5. Includes VCCO current without output loading.



**ispMACH 4000V/B/C External Switching Characteristics****Over Recommended Operating Conditions**

Parameter	Description <sup>1, 2, 3</sup>	-25		-27		-3		-35		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>PD</sub>	5-PT bypass combinatorial propagation delay	—	2.5	—	2.7	—	3.0	—	3.5	ns
t <sub>PD_MG</sub>	20-PT combinatorial propagation delay through macrocell	—	3.2	—	3.5	—	3.8	—	4.2	ns
t <sub>S</sub>	GLB register setup time before clock	1.8	—	1.8	—	2.0	—	2.0	—	ns
t <sub>ST</sub>	GLB register setup time before clock with T-type register	2.0	—	2.0	—	2.2	—	2.2	—	ns
t <sub>SIR</sub>	GLB register setup time before clock, input register path	0.7	—	1.0	—	1.0	—	1.0	—	ns
t <sub>SIRZ</sub>	GLB register setup time before clock with zero hold	1.7	—	2.0	—	2.0	—	2.0	—	ns
t <sub>H</sub>	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	0.0	—	ns
t <sub>HT</sub>	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	0.0	—	ns
t <sub>HIR</sub>	GLB register hold time after clock, input register path	0.9	—	1.0	—	1.0	—	1.0	—	ns
t <sub>HIRZ</sub>	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	0.0	—	ns
t <sub>CO</sub>	GLB register clock-to-output delay	—	2.2	—	2.7	—	2.7	—	2.7	ns
t <sub>R</sub>	External reset pin to output delay	—	3.5	—	4.0	—	4.4	—	4.5	ns
t <sub>RW</sub>	External reset pulse duration	1.5	—	1.5	—	1.5	—	1.5	-	ns
t <sub>PTOE/DIS</sub>	Input to output local product term output enable/disable	—	4.0	—	4.5	—	5.0	—	5.5	ns
t <sub>GPTOE/DIS</sub>	Input to output global product term output enable/disable	—	5.0	—	6.5	—	8.0	—	8.0	ns
t <sub>GOE/DIS</sub>	Global OE input to output enable/disable	—	3.0	—	3.5	—	4.0	—	4.5	ns
t <sub>CW</sub>	Global clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
t <sub>GW</sub>	Global gate width low (for low transparent) or high (for high transparent)	1.1	—	1.3	—	1.3	—	1.3	—	ns
t <sub>WIR</sub>	Input register clock width, high or low	1.1	—	1.3	—	1.3	—	1.3	—	ns
f <sub>MAX</sub> <sup>4</sup>	Clock frequency with internal feedback	—	400	—	333	—	322	—	322	MHz
f <sub>MAX</sub> (Ext.)	Clock frequency with external feedback, [1 / (t <sub>S</sub> + t <sub>CO</sub> )]	—	250	—	222	—	212	—	212	MHz

1. Timing numbers are based on default LVCMS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.3.2

2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

**ispMACH 4000V/B/C External Switching Characteristics (Cont.)****Over Recommended Operating Conditions**

Parameter	Description <sup>1, 2, 3</sup>	-5		-75		-10		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t <sub>PD</sub>	5-PT bypass combinatorial propagation delay	—	5.0	—	7.5	—	10.0	ns
t <sub>PD_MG</sub>	20-PT combinatorial propagation delay through macrocell	—	5.5	—	8.0	—	10.5	ns
t <sub>S</sub>	GLB register setup time before clock	3.0	—	4.5	—	5.5	—	ns
t <sub>ST</sub>	GLB register setup time before clock with T-type register	3.2	—	4.7	—	5.5	—	ns
t <sub>SIR</sub>	GLB register setup time before clock, input register path	1.2	—	1.7	—	1.7	—	ns
t <sub>SIRZ</sub>	GLB register setup time before clock with zero hold	2.2	—	2.7	—	2.7	—	ns
t <sub>H</sub>	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
t <sub>HT</sub>	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
t <sub>HIR</sub>	GLB register hold time after clock, input register path	1.0	—	1.0	—	1.0	—	ns
t <sub>HIRZ</sub>	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
t <sub>CO</sub>	GLB register clock-to-output delay	—	3.4	—	4.5	—	6.0	ns
t <sub>R</sub>	External reset pin to output delay	—	6.3	—	9.0	—	10.5	ns
t <sub>RW</sub>	External reset pulse duration	2.0	—	4.0	—	4.0	—	ns
t <sub>PTOE/DIS</sub>	Input to output local product term output enable/disable	—	7.0	—	9.0	—	10.5	ns
t <sub>GPTOE/DIS</sub>	Input to output global product term output enable/disable	—	9.0	—	10.3	—	12.0	ns
t <sub>GOE/DIS</sub>	Global OE input to output enable/disable	—	5.0	—	7.0	—	8.0	ns
t <sub>CW</sub>	Global clock width, high or low	2.2	—	2.8	—	4.0	—	ns
t <sub>GW</sub>	Global gate width low (for low transparent) or high (for high transparent)	2.2	—	2.8	—	4.0	—	ns
t <sub>WIR</sub>	Input register clock width, high or low	2.2	—	2.8	—	4.0	—	ns
f <sub>MAX</sub> <sup>4</sup>	Clock frequency with internal feedback	—	227	—	168	—	125	MHz
f <sub>MAX</sub> (Ext.)	Clock frequency with external feedback, [1/ (t <sub>S</sub> + t <sub>CO</sub> )]	—	156	—	111	—	86	MHz

1. Timing numbers are based on default LVC MOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.3.2

2. Measured using standard switching circuit, assuming GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

**ispMACH 4000Z External Switching Characteristics****Over Recommended Operating Conditions**

Parameter	Description <sup>1, 2, 3</sup>	-35		-37		-42		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
$t_{PD}$	5-PT bypass combinatorial propagation delay	—	3.5	—	3.7	—	4.2	ns
$t_{PD\_MC}$	20-PT combinatorial propagation delay through macrocell	—	4.4	—	4.7	—	5.7	ns
$t_S$	GLB register setup time before clock	2.2	—	2.5	—	2.7	—	ns
$t_{ST}$	GLB register setup time before clock with T-type register	2.4	—	2.7	—	2.9	—	ns
$t_{SIR}$	GLB register setup time before clock, input register path	1.0	—	1.1	—	1.3	—	ns
$t_{SIRZ}$	GLB register setup time before clock with zero hold	2.0	—	2.1	—	2.6	—	ns
$t_H$	GLB register hold time after clock	0.0	—	0.0	—	0.0	—	ns
$t_{HT}$	GLB register hold time after clock with T-type register	0.0	—	0.0	—	0.0	—	ns
$t_{HIR}$	GLB register hold time after clock, input register path	1.0	—	1.0	—	1.3	—	ns
$t_{HIRZ}$	GLB register hold time after clock, input register path with zero hold	0.0	—	0.0	—	0.0	—	ns
$t_{CO}$	GLB register clock-to-output delay	—	3.0	—	3.2	—	3.5	ns
$t_R$	External reset pin to output delay	—	5.0	—	6.0	—	7.3	ns
$t_{RW}$	External reset pulse duration	1.5	—	1.7	—	2.0	—	ns
$t_{PTOE/DIS}$	Input to output local product term output enable/disable	—	7.0	—	8.0	—	8.0	ns
$t_{GPTOE/DIS}$	Input to output global product term output enable/disable	—	6.5	—	7.0	—	8.0	ns
$t_{GOE/DIS}$	Global OE input to output enable/disable	—	4.5	—	4.5	—	4.8	ns
$t_{CW}$	Global clock width, high or low	1.0	—	1.5	—	1.8	—	ns
$t_{GW}$	Global gate width low (for low transparent) or high (for high transparent)	1.0	—	1.5	—	1.8	—	ns
$t_{WIR}$	Input register clock width, high or low	1.0	—	1.5	—	1.8	—	ns
$f_{MAX}^4$	Clock frequency with internal feedback	—	267	—	250	—	220	MHz
$f_{MAX}$ (Ext.)	clock frequency with external feedback, $[1 / (t_S + t_{CO})]$	—	192	—	175	—	161	MHz

1. Timing numbers are based on default LVC MOS 1.8 I/O buffers. Use timing adjusters provided to calculate other standards.

Timing v.2.2

2. Measured using standard switching GRP loading of 1 and 1 output switching.

3. Pulse widths and clock widths less than minimum will cause unknown behavior.

4. Standard 16-bit counter using GRP feedback.

**ispMACH 4000Z Internal Timing Parameters (Cont.)**

Over Recommended Operating Conditions

Parameter	Description	-45		-5		-75		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
<b>In/Out Delays</b>								
$t_{IN}$	Input Buffer Delay	—	0.95	—	1.25	—	1.80	ns
$t_{GOE}$	Global OE Pin Delay	—	3.00	—	3.50	—	4.30	ns
$t_{GCLK\_IN}$	Global Clock Input Buffer Delay	—	1.95	—	2.05	—	2.15	ns
$t_{BUF}$	Delay through Output Buffer	—	1.10	—	1.00	—	1.30	ns
$t_{EN}$	Output Enable Time	—	2.50	—	2.50	—	2.70	ns
$t_{DIS}$	Output Disable Time	—	2.50	—	2.50	—	2.70	ns
<b>Routing/GLB Delays</b>								
$t_{ROUTE}$	Delay through GRP	—	2.25	—	2.05	—	2.50	ns
$t_{MCELL}$	Macrocell Delay	—	0.65	—	0.65	—	1.00	ns
$t_{INREG}$	Input Buffer to Macrocell Register Delay	—	1.00	—	1.00	—	1.00	ns
$t_{FBK}$	Internal Feedback Delay	—	0.35	—	0.05	—	0.05	ns
$t_{PD_b}$	5-PT Bypass Propagation Delay	—	0.20	—	0.70	—	1.90	ns
$t_{PDI}$	Macrocell Propagation Delay	—	0.45	—	0.65	—	1.00	ns
<b>Register/Latch Delays</b>								
$t_S$	D-Register Setup Time (Global Clock)	1.00	—	1.10	—	1.35	—	ns
$t_{S\_PT}$	D-Register Setup Time (Product Term Clock)	2.10	—	1.90	—	2.45	—	ns
$t_{ST}$	T-Register Setup Time (Global Clock)	1.20	—	1.30	—	1.55	—	ns
$t_{ST\_PT}$	T-register Setup Time (Product Term Clock)	2.30	—	2.10	—	2.75	—	ns
$t_H$	D-Register Hold Time	1.90	—	1.90	—	3.15	—	ns
$t_{HT}$	T-Resister Hold Time	1.90	—	1.90	—	3.15	—	ns
$t_{SIR}$	D-Input Register Setup Time (Global Clock)	1.30	—	1.10	—	0.75	—	ns
$t_{SIR\_PT}$	D-Input Register Setup Time (Product Term Clock)	1.45	—	1.45	—	1.45	—	ns
$t_{HIR}$	D-Input Register Hold Time (Global Clock)	1.30	—	1.50	—	1.95	—	ns
$t_{HIR\_PT}$	D-Input Register Hold Time (Product Term Clock)	1.00	—	1.00	—	1.18	—	ns
$t_{COi}$	Register Clock to Output/Feedback MUX Time	—	0.75	—	1.15	—	1.05	ns
$t_{CES}$	Clock Enable Setup Time	2.00	—	2.00	—	2.00	—	ns
$t_{CEH}$	Clock Enable Hold Time	0.00	—	0.00	—	0.00	—	ns
$t_{SL}$	Latch Setup Time (Global Clock)	1.00	—	1.00	—	1.65	—	ns
$t_{SL\_PT}$	Latch Setup Time (Product Term Clock)	2.10	—	1.90	—	2.15	—	ns
$t_{HL}$	Latch Hold Time	2.00	—	2.00	—	1.17	—	ns
$t_{GOi}$	Latch Gate to Output/Feedback MUX Time	—	0.33	—	0.33	—	0.33	ns
$t_{PDLi}$	Propagation Delay through Transparent Latch to Output/Feedback MUX	—	0.25	—	0.25	—	0.25	ns
$t_{SRi}$	Asynchronous Reset or Set to Output/Feedback MUX Delay	—	0.97	—	0.97	—	0.28	ns
$t_{SRR}$	Asynchronous Reset or Set Recovery Delay	—	1.80	—	1.80	—	1.67	ns
<b>Control Delays</b>								
$t_{BCLK}$	GLB PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
$t_{PTCLK}$	Macrocell PT Clock Delay	—	1.55	—	1.55	—	1.25	ns
$t_{BSR}$	GLB PT Set/Reset Delay	—	1.83	—	1.83	—	1.83	ns
$t_{PTSR}$	Macrocell PT Set/Reset Delay	—	1.83	—	1.83	—	2.72	ns
$t_{GPTOE}$	Global PT OE Delay	—	4.30	—	4.20	—	3.50	ns

**ispMACH 4000V/B/C/Z Power Supply and NC Connections<sup>1</sup>**

Signal	44-pin TQFP <sup>2</sup>	48-pin TQFP <sup>2</sup>	56-ball csBGA <sup>3</sup>	100-pin TQFP <sup>2</sup>	128-pin TQFP <sup>2</sup>
VCC	11, 33	12, 36	K2, A9	25, 40, 75, 90	32, 51, 96, 115
VCCO0 VCCO (Bank 0)	6	6	F3	13, 33, 95	3, 17, 30, 41, 122
VCCO1 VCCO (Bank 1)	28	30	E8	45, 63, 83	58, 67, 81, 94, 105
GND	12, 34	13, 37	H3, C8	1, 26, 51, 76	1, 33, 65, 97
GND (Bank 0)	5	5	D3	7, 18, 32, 96	10, 24, 40, 113, 123
GND (Bank 1)	27	29	G8	46, 57, 68, 82	49, 59, 74, 88, 104
NC	—	—	<b>4032Z:</b> A8, B10, E1, E3, F8, F10, J1, K3	—	—

1. All grounds must be electrically connected at the board level. However, for the purposes of I/O current loading, grounds are associated with the bank shown.

2. Pin orientation follows the conventional order from pin 1 marking of the top side view and counter-clockwise.

3. Pin orientation A1 starts from the upper left corner of the top side view with alphabetical order ascending vertically and numerical order ascending horizontally.

**ispMACH 4128V/B/C Logic Signal Connections: 128-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4128V/B/C	
		GLB/MC/Pad	ORP
62	1	E10	E^8
63	1	E12	E^9
64	1	E14	E^11
65	1	GND	-
66	1	TMS	-
67	1	VCCO (Bank 1)	-
68	1	F0	F^0
69	1	F1	F^1
70	1	F2	F^2
71	1	F4	F^3
72	1	F5	F^4
73	1	F6	F^5
74	1	GND (Bank 1)	-
75	1	F8	F^6
76	1	F9	F^7
77	1	F10	F^8
78	1	F12	F^9
79	1	F13	F^10
80	1	F14	F^11
81	1	VCCO (Bank 1)	-
82	1	G14	G^11
83	1	G13	G^10
84	1	G12	G^9
85	1	G10	G^8
86	1	G9	G^7
87	1	G8	G^6
88	1	GND (Bank 1)	-
89	1	G6	G^5
90	1	G5	G^4
91	1	G4	G^3
92	1	G2	G^2
93	1	G0	G^0
94	1	VCCO (Bank 1)	-
95	1	TDO	-
96	1	VCC	-
97	1	GND	-
98	1	H14	H^11
99	1	H13	H^10
100	1	H12	H^9
101	1	H10	H^8
102	1	H9	H^7
103	1	H8	H^6
104	1	GND (Bank 1)	-

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:  
132-Ball csBGA (Cont.)**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
E3	0	NC	-	B8	B^6	D12	D^6
F2	0	A12	A^12	B9	B^7	D10	D^5
F1	0	A13	A^13	B10	B^8	D8	D^4
F3	0	A14	A^14	B12	B^9	D6	D^3
G1	0	A15	A^15	B13	B^10	D4	D^2
G2	0	I	-	B14	B^11	D2	D^1
G3	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
H2	0	NC	-	C14	C^11	E2	E^1
H1	0	B15	B^15	C13	C^10	E4	E^2
H3	0	B14	B^14	C12	C^9	E6	E^3
J1	0	B13	B^13	C10	C^8	E8	E^4
J2	0	B12	B^12	C9	C^7	E10	E^5
J3	0	NC	-	C8	C^6	E12	E^6
K2	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
K1	0	NC	-	C6	C^5	F2	F^1
K3	0	B11	B^11	C5	C^4	F4	F^2
L2	0	B10	B^10	C4	C^3	F6	F^3
L1	0	B9	B^9	C2	C^2	F8	F^4
L3	0	B8	B^8	C1	C^1	F10	F^5
M1	0	I	-	C0	C^0	F12	F^6
M2	0	NC	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
N1	-	TCK	-	TCK	-	TCK	-
P1	-	VCC	-	VCC	-	VCC	-
P2	-	GND	-	GND	-	GND	-
N2	0	I	-	D14	D^11	G12	G^6
P3	0	B7	B^7	D13	D^10	G10	G^5
M3	0	B6	B^6	D12	D^9	G8	G^4
N3	0	B5	B^5	D10	D^8	G6	G^3
P4	0	B4	B^4	D9	D^7	G4	G^2
M4	0	NC	-	D8	D^6	G2	G^1
N4	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
P5	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
N5	0	NC	-	D6	D^5	H12	H^6
M5	0	B3	B^3	D5	D^4	H10	H^5
N6	0	B2	B^2	D4	D^3	H8	H^4
P6	0	B1	B^1	D2	D^2	H6	H^3
M6	0	B0	B^0	D1	D^1	H4	H^2
P7	0	NC	-	D0	D^0	H2	H^1
N7	0	CLK1/I	-	CLK1/I	-	CLK1/I	-
M7	1	CLK2/I	-	CLK2/I	-	CLK2/I	-
N8	-	VCC	-	VCC	-	VCC	-

**ispMACH 4064Z, 4128Z and 4256Z Logic Signal Connections:  
132-Ball csBGA (Cont.)**

Ball Number	Bank Number	ispMACH 4064Z		ispMACH 4128Z		ispMACH 4256Z	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
D13	1	D10	D^10	G4	G^3	N6	N^3
D14	1	D9	D^9	G2	G^2	N8	N^4
D12	1	D8	D^8	G1	G^1	N10	N^5
C14	1	I	-	G0	G^0	N12	N^6
C13	1	NC	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
B14	-	TDO	-	TDO	-	TDO	-
A14	-	VCC	-	VCC	-	VCC	-
A13	-	GND	-	GND	-	GND	-
B13	1	NC	-	H14	H^11	O12	O^6
A12	1	I	-	H13	H^10	O10	O^5
C12	1	D7	D^7	H12	H^9	O8	O^4
B12	1	D6	D^6	H10	H^8	O6	O^3
A11	1	D5	D^5	H9	H^7	O4	O^2
C11	1	D4	D^4	H8	H^6	O2	O^1
B11	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
A10	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
B10	1	NC	-	H6	H^5	P12	P^6
C10	1	NC	-	H5	H^4	P10	P^5
B9	1	D3	D^3	H4	H^3	P8	P^4
A9	1	D2	D^2	H2	H^2	P6	P^3
C9	1	D1	D^1	H1	H^1	P4	P^2
A8	1	D0/GOE1	D^0	H0/GOE1	H^0	P2/GOE1	P^1
B8	1	CLK3/I	-	CLK3/I	-	CLK3/I	-
C8	0	CLK0/I	-	CLK0/I	-	CLK0/I	-
B7	-	VCC	-	VCC	-	VCC	-
A7	0	NC <sup>1</sup>	-	NC <sup>1</sup>	-	I <sup>1</sup>	-
C7	0	A0/GOE0	A^0	A0/GOE0	A^0	A2/GOE0	A^1
A6	0	A1	A^1	A1	A^1	A4	A^2
B6	0	A2	A^2	A2	A^2	A6	A^3
C6	0	A3	A^3	A4	A^3	A8	A^4
B5	0	NC	-	A5	A^4	A10	A^5
A5	0	NC	-	A6	A^5	A12	A^6
C5	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
B4	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
A4	0	NC	-	A8	A^6	B2	B^1
C4	0	A4	A^4	A9	A^7	B4	B^2
A3	0	A5	A^5	A10	A^8	B6	B^3
B3	0	A6	A^6	A12	A^9	B8	B^4
A2	0	A7	A^7	A13	A^10	B10	B^5
A1	0	NC	-	A14	A^11	B12	B^6

1. For device migration considerations, these NC pins are input signal pins in ispMACH 4256Z device.

**ispMACH 4128V and 4256V Logic Signal Connections: 144-Pin TQFP**

Pin Number	Bank Number	ispMACH 4128V		ispMACH 4256V	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
1	-	GND	-	GND	-
2	-	TDI	-	TDI	-
3	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
4	0	B0	B^0	C12	C^6
5	0	B1	B^1	C10	C^5
6	0	B2	B^2	C8	C^4
7	0	B4	B^3	C6	C^3
8	0	B5	B^4	C4	C^2
9	0	B6	B^5	C2	C^1
10	0	GND (Bank 0)	-	GND (Bank 0)	-
11	0	B8	B^6	D14	D^7
12	0	B9	B^7	D12	D^6
13	0	B10	B^8	D10	D^5
14	0	B12	B^9	D8	D^4
15	0	B13	B^10	D6	D^3
16	0	B14	B^11	D4	D^2
17	-	NC <sup>2</sup>	-	I <sup>2</sup>	-
18	0	GND (Bank 0) <sup>1</sup>	-	NC <sup>1</sup>	-
19	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
20	0	NC <sup>2</sup>	-	I <sup>2</sup>	-
21	0	C14	C^11	E2	E^1
22	0	C13	C^10	E4	E^2
23	0	C12	C^9	E6	E^3
24	0	C10	C^8	E8	E^4
25	0	C9	C^7	E10	E^5
26	0	C8	C^6	E12	E^6
27	0	GND (Bank 0)	-	GND (Bank 0)	-
28	0	C6	C^5	F2	F^1
29	0	C5	C^4	F4	F^2
30	0	C4	C^3	F6	F^3
31	0	C2	C^2	F8	F^4
32	0	C1	C^1	F10	F^5
33	0	C0	C^0	F12	F^6
34	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-
35	-	TCK	-	TCK	-
36	-	VCC	-	VCC	-
37	-	GND	-	GND	-
38	0	NC <sup>2</sup>	-	I <sup>2</sup>	-
39	0	D14	D^11	G12	G^6
40	0	D13	D^10	G10	G^5
41	0	D12	D^9	G8	G^4
42	0	D10	D^8	G6	G^3

**ispMACH 4256V/B/C/Z, 4384V/B/C, 4512V/B/C, Logic Signal Connections:  
176-Pin TQFP (Cont.)**

Pin Number	Bank Number	ispMACH 4256V/B/C/Z		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
142	1	O0	O^0	GX0	GX^0	OX0	OX^0
143	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
144	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
145	1	P14	P^7	HX14	HX^7	PX14	PX^7
146	1	P12	P^6	HX12	HX^6	PX12	PX^6
147	1	P10	P^5	HX10	HX^5	PX10	PX^5
148	1	P8	P^4	HX8	HX^4	PX8	PX^4
149	1	P6	P^3	HX6	HX^3	PX6	PX^3
150	1	P4	P^2	HX4	HX^2	PX4	PX^2
151	1	P2/GOE1	P^1	HX2/GOE1	HX^1	PX2/GOE1	PX^1
152	1	P0	P^0	HX0	HX^0	PX0	PX^0
153	-	GND	-	GND	-	GND	-
154	1	CLK3/I	-	CLK3/I	-	CLK3/I	-
155	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
156	0	CLK0/I	-	CLK0/I	-	CLK0/I	-
157	-	VCC	-	VCC	-	VCC	-
158	0	A0	A^0	A0	A^0	A0	A^0
159	0	A2/GOE0	A^1	A2/GOE0	A^1	A2//GOE0	A^1
160	0	A4	A^2	A4	A^2	A4	A^2
161	0	A6	A^3	A6	A^3	A6	A^3
162	0	A8	A^4	A8	A^4	A8	A^4
163	0	A10	A^5	A10	A^5	A10	A^5
164	0	A12	A^6	A12	A^6	A12	A^6
165	0	A14	A^7	A14	A^7	A14	A^7
166	0	VCCO (Bank 0)	-	VCCO (Bank 0)	-	VCCO (Bank 0)	-
167	0	GND (Bank 0)	-	GND (Bank 0)	-	GND (Bank 0)	-
168	0	B0	B^0	B0	B^0	B0	B^0
169	0	B2	B^1	B2	B^1	B2	B^1
170	0	B4	B^2	B4	B^2	B4	B^2
171	0	B6	B^3	B6	B^3	B6	B^3
172	0	B8	B^4	B8	B^4	B8	B^4
173	0	B10	B^5	B10	B^5	B10	B^5
174	0	B12	B^6	B12	B^6	B12	B^6
175	0	B14	B^7	B14	B^7	B14	B^7
176	-	VCC	-	VCC	-	VCC	-

**ispMACH 4256V/B/C, 4384V/B/C, 4512V/B/C Logic Signal Connections:  
256-Ball ftBGA/fpBGA (Cont.)**

Ball Number	I/O Bank	ispMACH 4256V/B/C 128-I/O		ispMACH 4256V/B/C 160-I/O		ispMACH 4384V/B/C		ispMACH 4512V/B/C	
		GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP	GLB/MC/Pad	ORP
R5	0	NC	-	NC	-	NC	-	L4	L^1
T5	0	NC	-	NC	-	I2	I^1	L8	L^2
R6	0	NC	-	NC	-	I0	I^0	L12	L^3
T6	0	NC	-	H14	H^9	G12	G^6	M8	M^2
N7	0	NC	-	H12	H^8	G14	G^7	M12	M^3
P7	0	H14	H^7	H10	H^7	L14	L^7	P14	P^7
R7	0	H12	H^6	H9	H^6	L12	L^6	P12	P^6
L8	0	H10	H^5	H8	H^5	L10	L^5	P10	P^5
T7	0	H8	H^4	H6	H^4	L8	L^4	P8	P^4
M8	0	H6	H^3	H4	H^3	L6	L^3	P6	P^3
N8	0	H4	H^2	H2	H^2	L4	L^2	P4	P^2
R8	0	H2	H^1	H1	H^1	L2	L^1	P2	P^1
P8	0	H0	H^0	H0	H^0	L0	L^0	P0	P^0
-	-	GND	-	GND	-	GND	-	GND	-
T8	0	CLK1/I	-	CLK1/I	-	CLK1/I	-	CLK1/I	-
-	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
N9	1	CLK2/I	-	CLK2/I	-	CLK2/I	-	CLK2/I	-
-	-	VCC	-	VCC	-	VCC	-	VCC	-
P9	1	I0	I^0	I0	I^0	M0	M^0	AX0	AX^0
R9	1	I2	I^1	I1	I^1	M2	M^1	AX2	AX^1
T9	1	I4	I^2	I2	I^2	M4	M^2	AX4	AX^2
T10	1	I6	I^3	I4	I^3	M6	M^3	AX6	AX^3
R10	1	I8	I^4	I6	I^4	M8	M^4	AX8	AX^4
M9	1	I10	I^5	I8	I^5	M10	M^5	AX10	AX^5
P10	1	I12	I^6	I9	I^6	M12	M^6	AX12	AX^6
L9	1	I14	I^7	I10	I^7	M14	M^7	AX14	AX^7
N10	1	NC	-	I12	I^8	BX14	BX^7	DX0	DX^0
T11	1	NC	-	I14	I^9	BX12	BX^6	DX4	DX^1
R11	1	NC	-	NC	-	P0	P^0	EX0	EX^0
T12	1	NC	-	NC	-	P2	P^1	EX4	EX^1
N12	1	NC	-	NC	-	NC	-	EX8	EX^2
-	1	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-	VCCO (Bank 1)	-
-	1	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-	GND (Bank 1)	-
R12	1	NC	-	NC	-	NC	-	EX12	EX^3
T13	1	NC	-	J0	J^0	BX10	BX^5	DX8	DX^2
P12	1	NC	-	J1	J^1	BX8	BX^4	DX12	DX^3
M10	1	J0	J^0	J2	J^2	N0	N^0	BX0	BX^0
R13	1	J2	J^1	J4	J^3	N2	N^1	BX2	BX^1
L10	1	J4	J^2	J6	J^4	N4	N^2	BX4	BX^2
T14	1	J6	J^3	J8	J^5	N6	N^3	BX6	BX^3
M11	1	J8	J^4	J9	J^6	N8	N^4	BX8	BX^4

## Ordering Information

Note: ispMACH 4000 devices are all dual marked except the slowest commercial speed grade ispMACH 4000Z devices. For example, the commercial speed grade LC4128C-5T100C is also marked with the industrial grade -75I. The commercial grade is always one speed grade faster than the associated dual mark industrial grade. The slowest commercial speed grade ispMACH 4000Z devices are marked as commercial grade only.

### Conventional Packaging

#### ispMACH 4000ZC (Zero Power, 1.8V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-35M56C	32	1.8	3.5	csBGA	56	32	C
	LC4032ZC-5M56C	32	1.8	5	csBGA	56	32	C
	LC4032ZC-75M56C	32	1.8	7.5	csBGA	56	32	C
	LC4032ZC-35T48C	32	1.8	3.5	TQFP	48	32	C
	LC4032ZC-5T48C	32	1.8	5	TQFP	48	32	C
	LC4032ZC-75T48C	32	1.8	7.5	TQFP	48	32	C
LC4064ZC	LC4064ZC-37M132C	64	1.8	3.7	csBGA	132	64	C
	LC4064ZC-5M132C	64	1.8	5	csBGA	132	64	C
	LC4064ZC-75M132C	64	1.8	7.5	csBGA	132	64	C
	LC4064ZC-37T100C	64	1.8	3.7	TQFP	100	64	C
	LC4064ZC-5T100C	64	1.8	5	TQFP	100	64	C
	LC4064ZC-75T100C	64	1.8	7.5	TQFP	100	64	C
	LC4064ZC-37M56C	64	1.8	3.7	csBGA	56	32	C
	LC4064ZC-5M56C	64	1.8	5	csBGA	56	32	C
	LC4064ZC-75M56C	64	1.8	7.5	csBGA	56	32	C
	LC4064ZC-37T48C	64	1.8	3.7	TQFP	48	32	C
	LC4064ZC-5T48C	64	1.8	5	TQFP	48	32	C
	LC4064ZC-75T48C	64	1.8	7.5	TQFP	48	32	C
LC4128ZC	LC4128ZC-42M132C	128	1.8	4.2	csBGA	132	96	C
	LC4128ZC-75M132C	128	1.8	7.5	csBGA	132	96	C
	LC4128ZC-42T100C	128	1.8	4.2	TQFP	100	64	C
	LC4128ZC-75T100C	128	1.8	7.5	TQFP	100	64	C
LC4256ZC	LC4256ZC-45T176C	256	1.8	4.5	TQFP	176	128	C
	LC4256ZC-75T176C	256	1.8	7.5	TQFP	176	128	C
	LC4256ZC-45M132C	256	1.8	4.5	csBGA	132	96	C
	LC4256ZC-75M132C	256	1.8	7.5	csBGA	132	96	C
	LC4256ZC-45T100C	256	1.8	4.5	TQFP	100	64	C
	LC4256ZC-75T100C	256	1.8	7.5	TQFP	100	64	C

#### ispMACH 4000ZC (1.8V, Zero Power) Industrial Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-5M56I	32	1.8	5	csBGA	56	32	I
	LC4032ZC-75M56I	32	1.8	7.5	csBGA	56	32	I
	LC4032ZC-5T48I	32	1.8	5	TQFP	48	32	I
	LC4032ZC-75T48I	32	1.8	7.5	TQFP	48	32	I

## ispMACH 4000ZC (1.8V, Zero Power) Industrial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4064ZC	LC4064ZC-5M132I	64	1.8	5	csBGA	132	64	I
	LC4064ZC-75M132I	64	1.8	7.5	csBGA	132	64	I
	LC4064ZC-5T100I	64	1.8	5	TQFP	100	64	I
	LC4064ZC-75T100I	64	1.8	7.5	TQFP	100	64	I
	LC4064ZC-5M56I	64	1.8	5	csBGA	56	34	I
	LC4064ZC-75M56I	64	1.8	7.5	csBGA	56	34	I
	LC4064ZC-5T48I	64	1.8	5	TQFP	48	32	I
	LC4064ZC-75T48I	64	1.8	7.5	TQFP	48	32	I
LC4128ZC	LC4128ZC-75M132I	128	1.8	7.5	csBGA	132	96	I
	LC4128ZC-75T100I	128	1.8	7.5	TQFP	100	64	I
LC4256ZC	LC4256ZC-75T176I	256	1.8	7.5	TQFP	176	128	I
	LC4256ZC-75M132I	256	1.8	7.5	csBGA	132	96	I
	LC4256ZC-75T100I	256	1.8	7.5	TQFP	100	64	I

## ispMACH 4000ZC (1.8V, Zero Power) Extended Temperature Devices

Family	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032ZC	LC4032ZC-75T48E	32	1.8	7.5	TQFP	48	32	E
LC4064ZC	LC4064ZC-75T100E	64	1.8	7.5	TQFP	100	64	E
	LC4064ZC-75T48E	64	1.8	7.5	TQFP	48	32	E
LC4128ZC	LC4128ZC-75T100E	128	1.8	7.5	TQFP	100	64	E
LC4256ZC	LC4256ZC-75T176E	256	1.8	7.5	TQFP	176	128	E
	LC4256ZC-75T100E	256	1.8	7.5	TQFP	100	64	E

## ispMACH 4000C (1.8V) Commercial Devices

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032C	LC4032C-25T48C	32	1.8	2.5	TQFP	48	32	C
	LC4032C-5T48C	32	1.8	5	TQFP	48	32	C
	LC4032C-75T48C	32	1.8	7.5	TQFP	48	32	C
	LC4032C-25T44C	32	1.8	2.5	TQFP	44	30	C
	LC4032C-5T44C	32	1.8	5	TQFP	44	30	C
	LC4032C-75T44C	32	1.8	7.5	TQFP	44	30	C
LC4064C	LC4064C-25T100C	64	1.8	2.5	TQFP	100	64	C
	LC4064C-5T100C	64	1.8	5	TQFP	100	64	C
	LC4064C-75T100C	64	1.8	7.5	TQFP	100	64	C
	LC4064C-25T48C	64	1.8	2.5	TQFP	48	32	C
	LC4064C-5T48C	64	1.8	5	TQFP	48	32	C
	LC4064C-75T48C	64	1.8	7.5	TQFP	48	32	C
	LC4064C-25T44C	64	1.8	2.5	TQFP	44	30	C
	LC4064C-5T44C	64	1.8	5	TQFP	44	30	C
	LC4064C-75T44C	64	1.8	7.5	TQFP	44	30	C

## ispMACH 4000V (3.3V) Commercial Devices (Cont.)

Device	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4512V	LC4512V-35FT256C	512	3.3	3.5	ftBGA	256	208	C
	LC4512V-5FT256C	512	3.3	5	ftBGA	256	208	C
	LC4512V-75FT256C	512	3.3	7.5	ftBGA	256	208	C
	LC4512V-35F256C <sup>1</sup>	512	3.3	3.5	fpBGA	256	208	C
	LC4512V-5F256C <sup>1</sup>	512	3.3	5	fpBGA	256	208	C
	LC4512V-75F256C <sup>1</sup>	512	3.3	7.5	fpBGA	256	208	C
	LC4512V-35T176C	512	3.3	3.5	TQFP	176	128	C
	LC4512V-5T176C	512	3.3	5	TQFP	176	128	C
	LC4512V-75T176C	512	3.3	7.5	TQFP	176	128	C

1. Use ftBGA package. fpBGA package devices have been discontinued via PCN#14A-07.

## ispMACH 4000V (3.3V) Industrial Devices

Family	Part Number	Macrocells	Voltage	t <sub>PD</sub>	Package	Pin/Ball Count	I/O	Grade
LC4032V	LC4032V-5T48I	32	3.3	5	TQFP	48	32	I
	LC4032V-75T48I	32	3.3	7.5	TQFP	48	32	I
	LC4032V-10T48I	32	3.3	10	TQFP	48	32	I
	LC4032V-5T44I	32	3.3	5	TQFP	44	30	I
	LC4032V-75T44I	32	3.3	7.5	TQFP	44	30	I
	LC4032V-10T44I	32	3.3	10	TQFP	44	30	I
LC4064V	LC4064V-5T100I	64	3.3	5	TQFP	100	64	I
	LC4064V-75T100I	64	3.3	7.5	TQFP	100	64	I
	LC4064V-10T100I	64	3.3	10	TQFP	100	64	I
	LC4064V-5T48I	64	3.3	5	TQFP	48	32	I
	LC4064V-75T48I	64	3.3	7.5	TQFP	48	32	I
	LC4064V-10T48I	64	3.3	10	TQFP	48	32	I
	LC4064V-5T44I	64	3.3	5	TQFP	44	30	I
	LC4064V-75T44I	64	3.3	7.5	TQFP	44	30	I
	LC4064V-10T44I	64	3.3	10	TQFP	44	30	I
LC4128V	LC4128V-5T144I	128	3.3	5	TQFP	144	96	I
	LC4128V-75T144I	128	3.3	7.5	TQFP	144	96	I
	LC4128V-10T144I	128	3.3	10	TQFP	144	96	I
	LC4128V-5T128I	128	3.3	5	TQFP	128	92	I
	LC4128V-75T128I	128	3.3	7.5	TQFP	128	92	I
	LC4128V-10T128I	128	3.3	10	TQFP	128	92	I
	LC4128V-5T100I	128	3.3	5	TQFP	100	64	I
	LC4128V-75T100I	128	3.3	7.5	TQFP	100	64	I
	LC4128V-10T100I	128	3.3	10	TQFP	100	64	I